

06-08-2001

ASSIGNMENT RECORDATIO



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To the Honorable Commissioner of Patents and Trademarks:

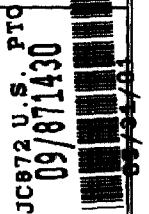
May 31, 2001
Attorney Dkt 5649-901

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Seung-hwan Lee
Yeong-kwan Kim
Dong-chan Kim
Young-wook ParkMRD
5-31-01

2. Name and address of receiving party(ies):

Samsung Electronics Co., Ltd.
416 Maetan-dong, Paldal-gu
Suwon-city, Kyungki-do
REPUBLIC OF KOREAAdditional name(s) of conveying party(ies) attached? Yes ☒ No

3. Nature of conveyance:

☒ Assignment
☐ Merger
☐ Security Agreement
☐ Change of Name
☐ Other _____

Execution Date: May 10, 2001

Additional name(s) & address(es) attached? Yes ☒ No4. Application Serial No. 09871430 Patent No.If this document is being filed together with a new application, the execution date of the application is: May 10, 2001; May 10, 2001; May 10, 2001 and May 14, 2001Additional numbers attached? Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Grant J. Scott
Myers Bigel Sibley & Sajovec
P. O. Box 37428
Raleigh NC 276276. Total number of applications and patents involved: 17. Total fee (37 CFR 3.41) \$40.00
☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit account number: 50-0220

DO NOT USE THIS SPACE

9. Statement and signature

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Grant J. Scott #36.925

Name of Person Signing

Signature

May 31, 2001

Date

Total number of pages including cover sheet, attachments and document: 3

06/05/2001 MABDI1 00000045 500220 09871430

03 FC:581 40.00 CH

ASSIGNMENT

THIS ASSIGNMENT, made by us, **Seung-hwan Lee**, citizen of the Republic of Korea, residing at B-1207, Eunha Apt., Yeoeuido-dong, Youngdeungpo-gu, Seoul, Republic of Korea; **Yeong-kwan Kim**, citizen of the Republic of Korea, residing at 645-803, Shinwon Apt., Shinnamusil, 965-2, Youngtong-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea; **Dong-chan Kim**, citizen of the Republic of Korea, residing at 3-901, Shindonga Apt., Bon-dong, Bongjak-gu, Seoul, Republic of Korea; and **Young-wook Park**, citizen of the Republic of Korea, residing at 541-706, Sungji Apt., Baekseol Maeul, Jeongjal-dong, Jangang-gu, Suwon-city, Kyungki-do, Republic of Korea

WITNESSETH: That,

WHEREAS, we are the joint inventors of certain new and useful improvements in **METHODS OF FORMING THIN FILMS BY ATOMIC LAYER DEPOSITION** for which an application for United States Letters Patent has been filed, or is being filed concurrently, in the United States Patent and Trademark Office. We hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known or to file this Assignment concurrently with the application, and

WHEREAS, **Samsung Electronics Co., Ltd.**, a Korean corporation having a principal place of business at 416 Maetan-dong, Paldal-gu, Suwon-City, Kyungki-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as

fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

We further covenant and agree to bind our heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, we have hereunto set our hands and seals on this 10th day of May, 2001.

Seung-hwan Lee
Seung-hwan Lee

Yeong Kwan Kim
Yeong-kwan Kim

Dong Chan Kim
Dong-chan Kim

Young wook Park
Young-wook Park

Witnessed by:

Date: _____

Date: _____